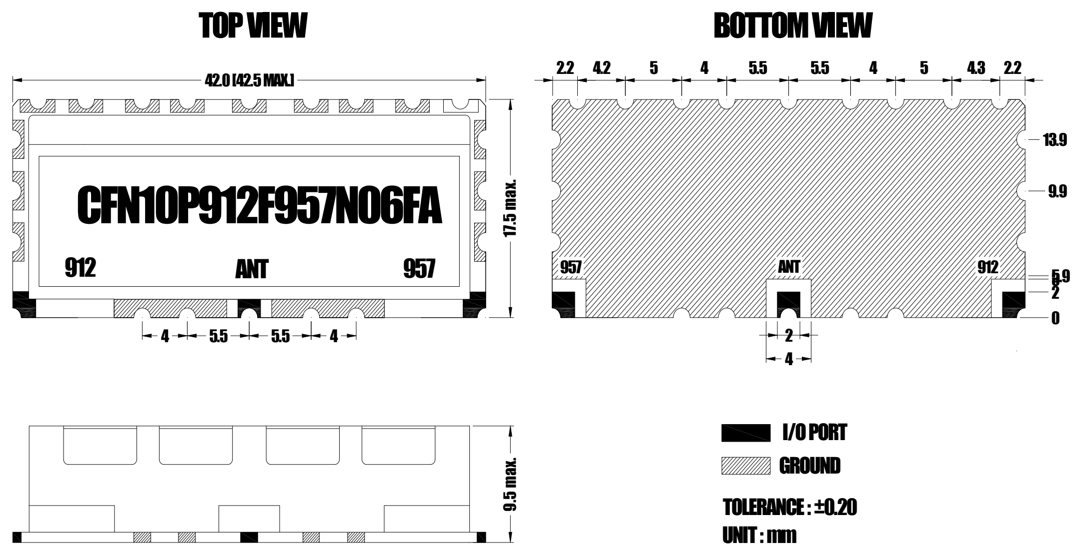
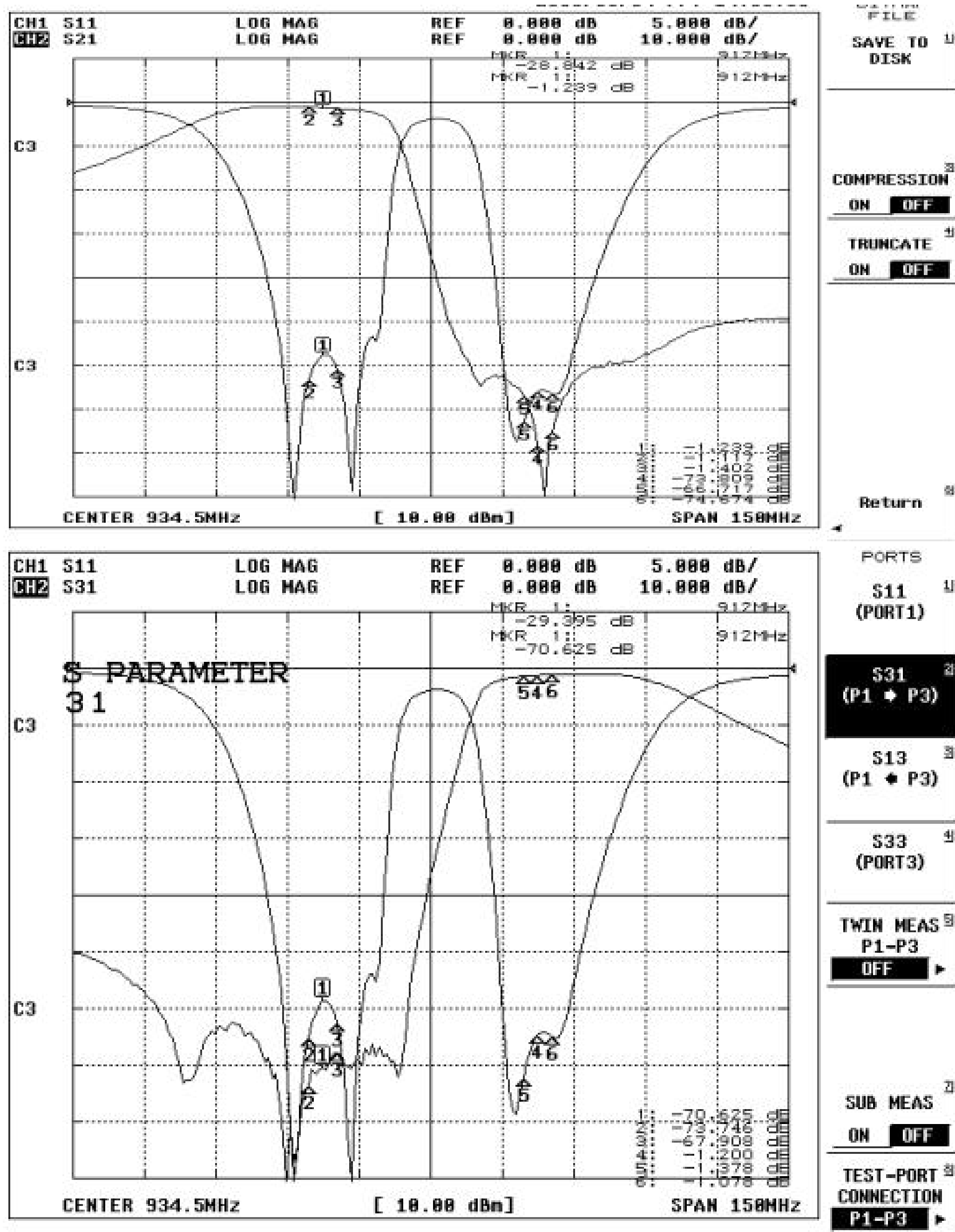
Electrical Specification

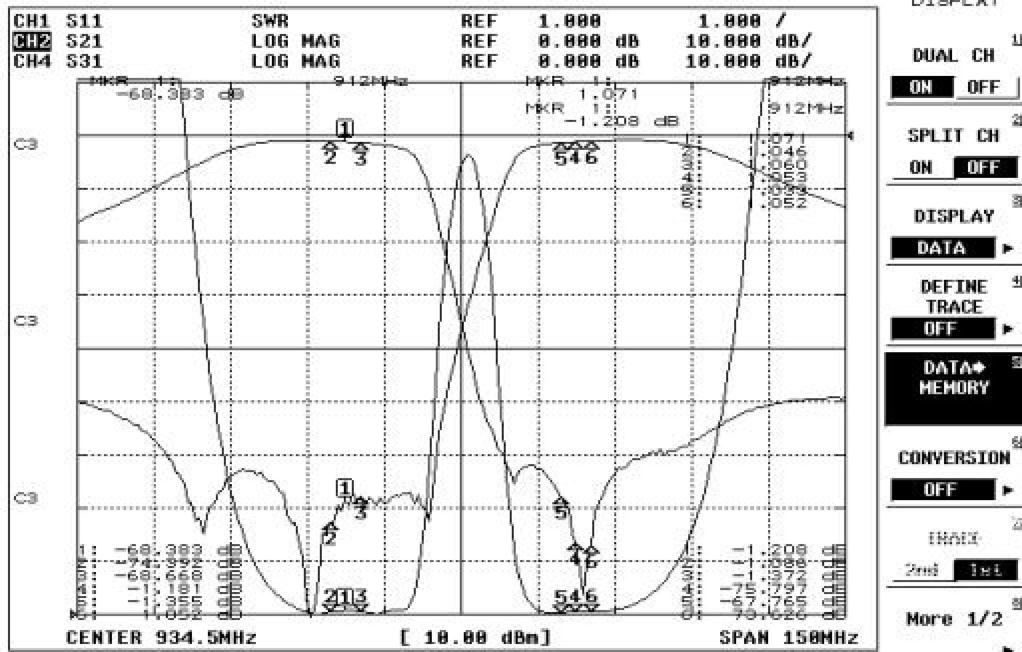
ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	912.0	957.5	MHz
Bandwidth [BW]	fo ±3.0[909 ~915]	fo ±3.0[954 ~960]	MHz
Insertion Loss in BW	1.8	1.8	dB max
Ripple in BW	0.8	0.8	dB max
Return Loss in BW	16.0	16.0	dB min
Attenuation ☑ Absolute Value ☐ Relative Value	60.0 dB min. @[954 ~ 960]	60.0dB min. @[909 ~ 915]	MHz
	dB min. @ [~]	dB min. @ [~]	MHz
	dB min. @ [~]	dB min. @ [~]	MHz
	dB min. @ [~]	dB min. @ [~]	MHz
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40℃ to +85℃		

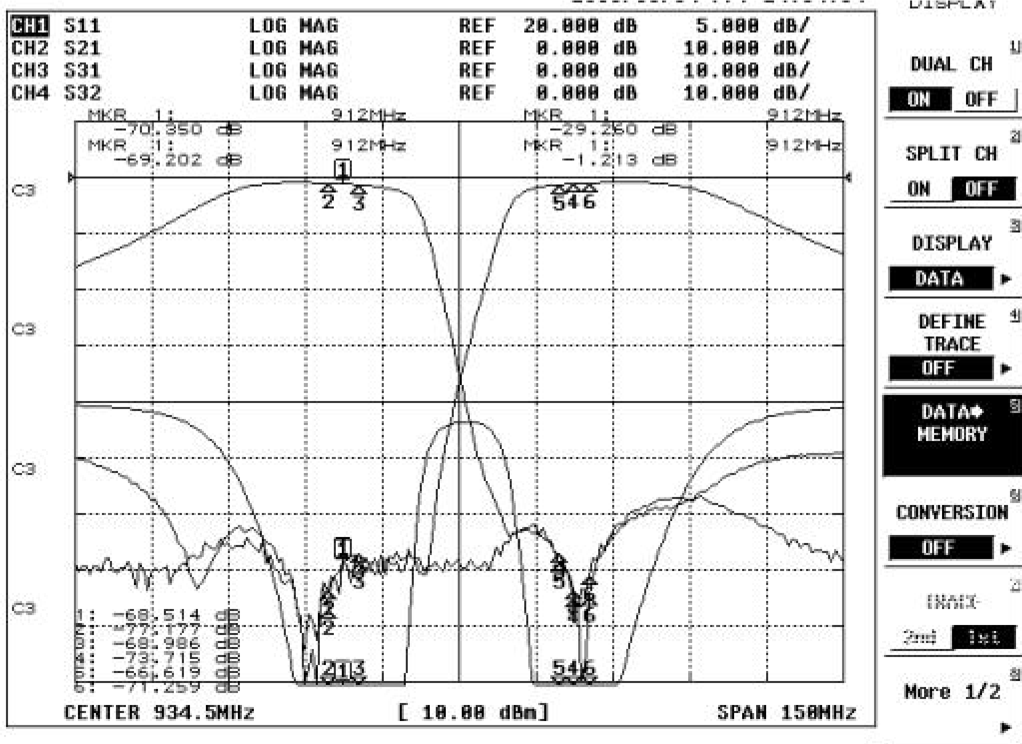
Mechanical Specification



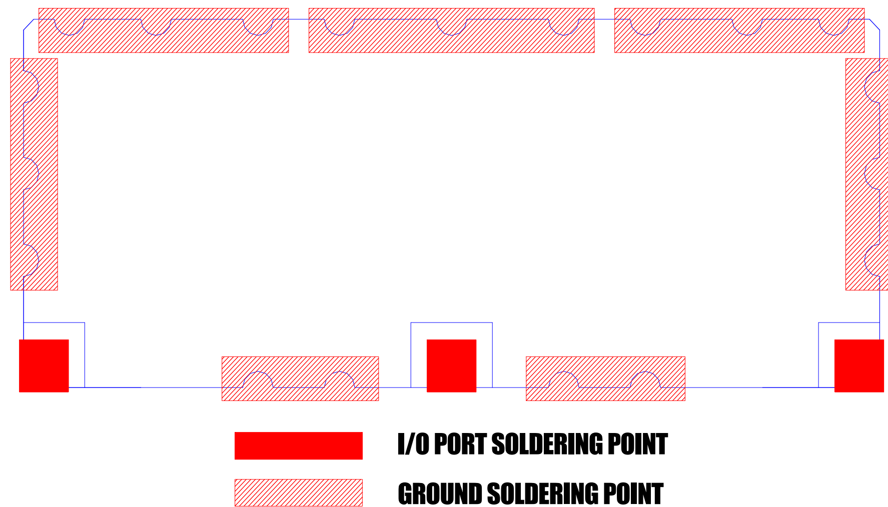
Plot Data



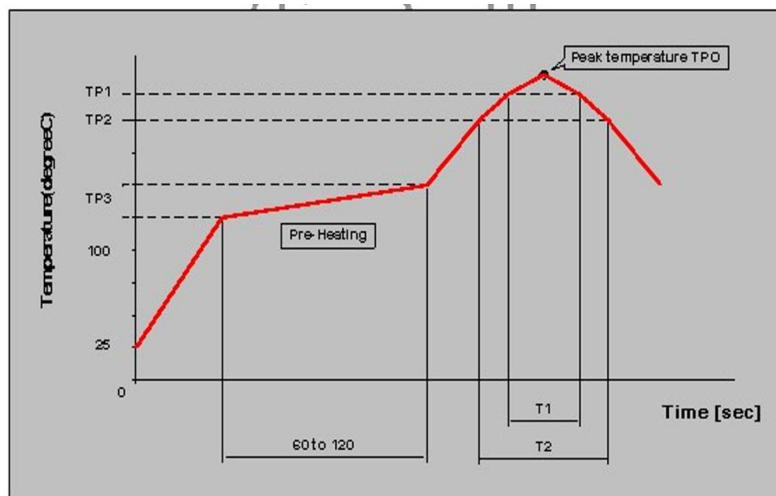

CH1 S11 SWR REF 1.000 1.000 /
CH2 S21 LOG MAG REF 0.000 dB 10.000 dB/
CH4 S31 LOG MAG REF 0.000 dB 10.000 dB/
MKR 1: 912MHz
-68.383 dB
MKR 1: 912MHz
1.071
MKR 1: 912MHz
-1.208 dB
1: 1.071
2: 1.046
3: 1.060
4: 1.053
6: 1.052
1: -68.383 dB
2: -74.392 dB
3: -68.668 dB
4: -1.181 dB
5: -1.355 dB
6: 1.052 dB
1: -1.208 dB
3: -1.372 dB
4: -75.797 dB
5: -67.765 dB
CENTER 934.5MHz
[10.00 dBm]
SPAN 150MHz
DUAL CH
ON OFF
SPLIT CH
ON OFF
DISPLAY
DATA
DEFINE TRACE
OFF
DATA→MEMORY
CONVERSION
OFF
More 1/2


CH1 S11 LOG MAG REF 20.000 dB 5.000 dB/
CH2 S21 LOG MAG REF 0.000 dB 10.000 dB/
CH3 S31 LOG MAG REF 0.000 dB 10.000 dB/
CH4 S32 LOG MAG REF 0.000 dB 10.000 dB/
MKR 1: 912MHz
-70.350 dB
MKR 1: 912MHz
-69.202 dB
MKR 1: 912MHz
-29.260 dB
MKR 1: 912MHz
-1.213 dB
1: -68.514 dB
2: -77.177 dB
3: -68.986 dB
4: -73.715 dB
5: -66.619 dB
6: -71.259 dB
CENTER 934.5MHz
[10.00 dBm]
SPAN 150MHz
DUAL CH
ON OFF
SPLIT CH
ON OFF
DISPLAY
DATA
DEFINE TRACE
OFF
DATA→MEMORY
CONVERSION
OFF
More 1/2

Recommanded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (℃)	TP1 (℃)	T1 (s)	TP2 (℃)	T2 (s)	TP3 (℃)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	___	___	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180